

In re Patent Application of:

**YOUNG ET AL.**

Serial No. 10/083,794

Filed: **FEBRUARY 27, 2002**

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**IN THE DESCRIPTION**

Insert the following paragraph on Page 12, line 22:

FIG. 19C shows a top view of FIG. 19B;

FIG. 19D shows a side view of the optical device removal tool being used to peel a portion of the adhesive pad from a circuit board;

FIG. 20A shows a cross-sectional view of one embodiment of a receiver optical bench;

Amend the paragraph on Page 40, line 12 to Page 41, line 8 as follows:

To break the mechanical attachment between the optical device 116 and the attachment region 606 on the circuit board 108, the optical device removal tool 900 first separates a small portion of the adhesive pad 604 or 605 from the attachment region 606, as illustrated in Figure 19D. Another knife tool, such as an exacto-knife, may then cut away a portion of the adhesive pad 604 or 605 at a location on the adhesive pad that is separate from where the optical device removal tool initially pried a portion of the attachment pad 604 or 605 (e.g., on an exposed end). The prying action by the optical device removal tool 900 acts to decrease the cutting force necessary to remove the optical device. The fork portions 910 of the optical device removal tool 900 are designed to be very narrow so as not to interfere with other components that are physically positioned adjacent to the removed optical device 116. Less force (and less resultant damage) is necessary to remove an adhesive-attached planar object (such as the optical device 116) affixed to a surface by peeling the planar adhesive at one edge than to shear the

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entire planar surface. Use of the optical device removal tool 900 limits the risk of damage to the circuit board 108 and optical device by shearing. With the peeling action, an edge portion of the adhesive pad 604 or 605 is peeled using the peeling blade 902. The optical device removal tool 900 can be used to pry the remainder of the optical device 116 from the circuit board 108. After removal of the optical device 116 from the circuit board 108, the optical device removal tool 900 can remove the adhesive pad 604 or 605 from the circuit board 108 or the optical device 116 to which it remains affixed.